#### Features

- Ferrite core.
- EP6 SMD type.
- Shielding for optimized EMC-behavior.
- 5 U-shape terminals.
- Operating temperature:- $40^{\circ}$ C ~ +125 $^{\circ}$ C (Including self-temperature rise).
- AEC-Q200 verified.

## Applications

- Ultrasonic Sensor.
- Ultrasonic Park Assist.
- Industrial distance measuring.
- Robotics.

#### Product Identification

$$\frac{\mathsf{YSTEP6}}{\mathsf{(1)}} - \boxed{\qquad} \boxed{\qquad} \boxed{\qquad} \boxed{\qquad} \boxed{\qquad} \boxed{\qquad} \boxed{\qquad} (4)$$

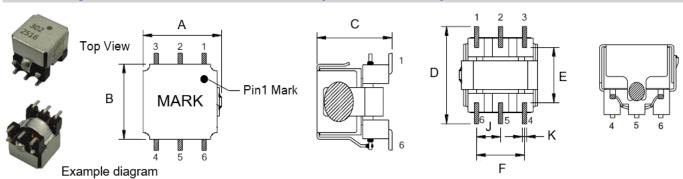
(1) : Type

(2): Inductance value

(3): Taping

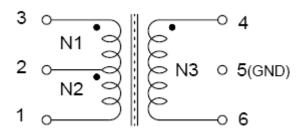
(4): Internal Code

#### ■ Shapes and Dimensions (Unit: mm)

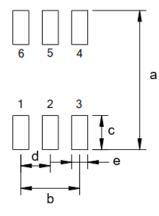


TYPE	A Max.	В	С	D Max.	Е Тур.	F Тур.	Ј Тур.	К
YSTEP6	7.6	6.6±0.5	6.9±0.3	9.1	4.8	4.4	2.2	0.5±0.1

## ■ ELECTRICAL SCHEMATICS



# **■ RECOMMENDED LAND PATTERN(Unit:mm)**



a ref.	9.2
b ref.	4.4
c ref.	2.5
d ref.	2.2
e ref.	1.2

(Top View)

# ■ ELECTRICAL CHARACTERISTICS

	Inductance	Lk	Test Conditions		DCR		Turns Ratio	
Part No.	mH	uH Max.	rest Conditions	Ω±20%			Turns Ratio	Maring
	4-6	4-6	KHz/1V	1-2	2-3	4-6	Pri-Sec	
YSTEP6-262T	2.45±0.15	150	52	0.60	0.60	21.5	1:1:7.84	262
YSTEP6-272T	2.70±8%	150	58	0.45	0.45	23.5	1:1:12	272
YSTEP6-272TC	2.70±8%	150	58	0.85	0.80	17.5	1:1:7	272C
YSTEP6-302T	3.0±10%	150	52	0.60	0.60	24.0	1:1:8.42	302
YSTEP6-318TA	3.18±8%	150	52	0.75	0.70	25.0	1:1:10.07	318A
YSTEP6-402T	4.0±5%	150	50	1.30	1.30	27.0	1:1:5.2	402
YSTEP6-412TC	4.1±8%	150	48	0.53	0.53	28.0	1:1:11.75	412C
YSTEP6-552T	5.5±8%	150	52	3.7 Max.	3.7 Max.	35 Max.	1:1:8	552

- Dielectric Strength: 250V D.C./1mA 1 Min (Coil-Coil)
- X Specifications other than the above will be furnished upon request.



# RELIABILITY TESTS

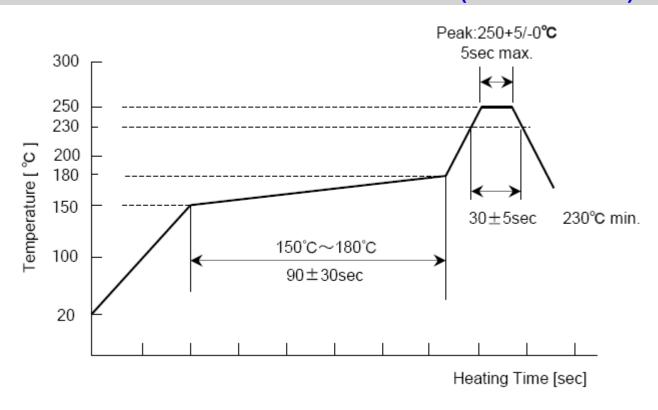
Item	Specified Value	Test Method and Conditions						
1.With standing	Al I Pr	300 V a.c. shall be applied for 60 sec between wires and core. (Cut						
voltage:	No abnormality	off current :1mA)						
		The test samples shall be exposed to reflow oven as shown in						
		below table.						
2.Resistance to	Inductance change: Within ± 5% .	300 250 200 180 100 100 100 100 100 100 1						
soldering heat	No significant abnormality in	Temperature range Duration						
	appearance.	150∼180°C 60∼120 sec						
		peak temperature 260± 5°C within 5 sec						
		230°C min 30±5 sec						
		Recovery:At least 1 hours of recovery under the standard condition						
		after the test, followed by the measurement within 48 hours.						
		The test samples shall be soldered to the test board by the						
		reflow. The test samples shall be placed at specified temperature for specified time by step 1 to step 4 as shown in below table in sequence. The temperature cycle shall be repeated 1000 cycles.						
	Inductance change:	Conditions of 1 cycle						
	Within ± 5%.	Step Temperature Duration						
3.Thermal shock	No significant Abnormality in	1 -40°C± 3°C 30± 3min						
	appearance.	2 Room Temperature within 3min						
		3 +125°C± 3°C 30± 3min						
		4 Room Temperature within 3min						
		Recovery: At least 1 hours of recovery under the standard condition						
		after the test, followed by the measurement within 48 hours.						
	Inductance change:	The coilshall be storedata temperature of 125± 2°C for 96± 2 h.						
	Within ± 5%.	And then the test samples shall be subjected to standard						
4.Dry heat	No significant abnormality in	atmospheric conditions for 1 h. after which measurement shall be						
	appearance.	made. The measurement shall be made within 1h after the recovery						
		period.						
		The test samples shall be placed in thermostatic oven set at						
		specified temperature and humidity as shown in below table.						
	Inductance change:	Temperature 60± 2°C						
5.Damp heat	Within ± 5% No significant	Humidity 95%RH						
	abnormality in appearance.	Time 96± 2hour						
		Recovery: At least 1 hours of recovery under the standard condition						
		after the test, followed by the measurement within 48 hours.						



# **■ RELIABILITY TESTS**

Item	Specified Value	Test Method and Conditions					
6.Cold	Inductance change: Within ± 5%.  No significant abnormality in appearance.	The coilshall be storedata temperature of -40± 2°C for 96± 2 h. And then the test samples shall be subjected to standard atmospheric conditions for 1 h. after which measurement shall be made. The measurement shall be made within 1 h after the recove					
7.Resistance to vibration	Inductance change: Within ± 5%.  No significant abnormality in appearance.	The test samples shall be soldered to the test board by the reflow Then it shall be submitted to below test conditions.  Frequency Range 10~55Hz  Total Amplitude 1.5mm(May not exceed acceleration196m/s2)  Sweeping Method 10Hz to 55Hz to 10Hz for 1 min.  X For 2 hours on each X,Y,and Z axis  Z					
8.Shock  9.Thermal	Inductance change: Within ±5%. No significant abnormality in appearance.  Terminals appear to be normal.	Pulse shape: Half sine Peak acceleration: 981m/s2 Duration of pulse: 6ms Three successive shocks shall be applied in both directions of 6 mutually perpendicular axis (atotal of 18 shocks). Axial pulling force 9.8N for 60± 0.5 s.					
strength  10.Solderability	95% or more of mounting terminal side shall be covered with fresh solder	he test samples shall be dipped influx,and then immersed nolten solder as shown in below table.  Solder Temperature 260± 5°C  Time 3± 0.5sec					

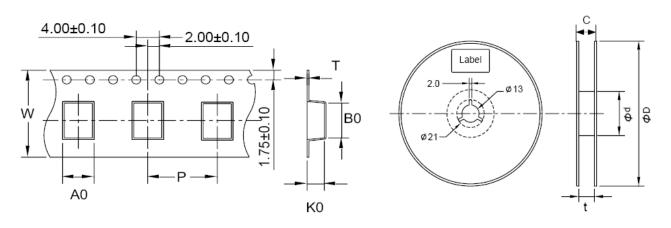
# ■ RECOMMENDED REFLOW CONDITION(Pb free solder)



#### **MANUAL SOLDERING**

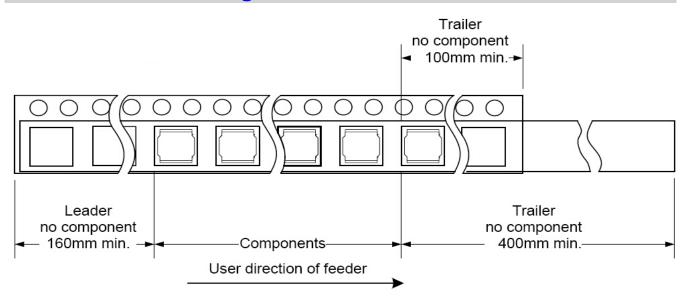
- ※ Solder iron temperature:380±5°C
- Soldering time:3±1sec

# **■ Taping Dimensions(Unit:mm)**

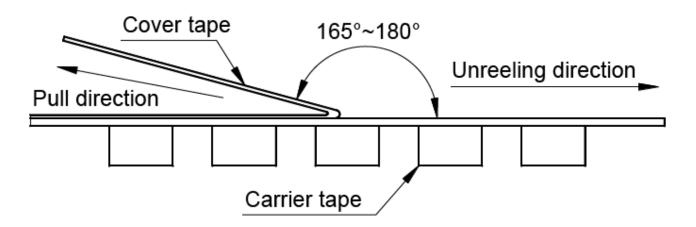


TYPE	A0	В0	K0	Р	Т	W	ΦD	Φd	С	Т	MPQ
YSTEP6	7.7	9.1	7.3	16	0.4	24	380	100	30.5	24.5	750

# Direction of rolling



# Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.